

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TDA38827	**Issued**	08. April 2022
MA#	MA005584040		
Package	PG-IQFN-22-2	**Weight***	85.39 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.210	0.25	0.25	2464	2464
chip_2	inorganic material	silicon	7440-21-3	0.393	0.46	0.46	4597	4597
chip_3	inorganic material	silicon	7440-21-3	1.552	1.82	1.82	18173	18173
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		115	
	non noble metal	zinc	7440-66-6	0.039	0.05		461	
	non noble metal	iron	7439-89-6	0.788	0.92		9229	
	non noble metal	copper	7440-50-8	31.997	37.47	38.45	374727	384532
wire	noble metal	gold	7440-57-5	0.368	0.43		4312	
	non noble metal	copper	7440-50-8	0.929	1.09	1.52	10883	15195
encapsulation	organic material	carbon black	1333-86-4	0.091	0.11		1061	
	plastics	epoxy resin	-	4.666	5.46		54646	
	inorganic material	silicondioxide	60676-86-0	40.544	47.49	53.06	474835	530542
leadfinish	noble metal	palladium	7440-05-3	0.003			31	
	noble metal	gold	7440-57-5	0.004			50	
	non noble metal	nickel	7440-02-0	0.077	0.09	0.09	905	986
plating	noble metal	silver	7440-22-4	0.588	0.69	0.69	6892	6892
solder	noble metal	silver	7440-22-4	0.078	0.09		915	
	non noble metal	tin	7440-31-5	0.156	0.18		1831	
	non noble metal	lead	7439-92-1	2.892	3.39	3.66	33873	36619
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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